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PATENT Lewis
10/28/99

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Norio FUKASAWA et al.

Serial No.: 09/029,608

Filed: May 15, 1998

Group Art Unit: 2812



For: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE

SECOND SUPPLEMENTAL PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

June 4, 1999

Sir:

11/15/1999 JHCWILLA 00000007 012340 09029608

01 FC:102

78.00 Under to the Supplemental Preliminary Amendment filed on February 26, 1999, please

amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 13-17 without prejudice or disclaimer and add new claims 103-108
as follows:

- C1
Cont'd
- 103. A mold for fabricating a semiconductor device comprising
- a first mold; and
 - a second mold which is located so as to face the first mold,
 - the second mold including a first half body having a shape corresponding to a shape of a substrate, and a second half body which is provided so as to surround the first half body and can be elevated with respect to the first half body,
 - the first and second half bodies cooperating with each other so that a cavity to be filled

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